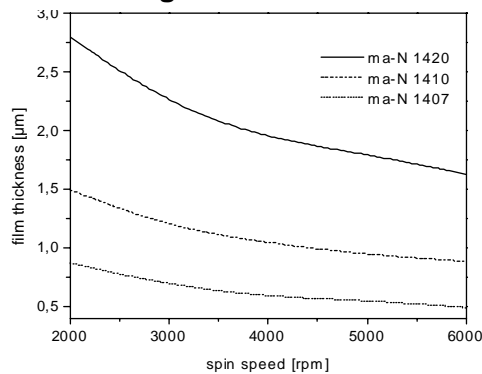


Product Information

Negative Tone Photoresist ma-N 1400

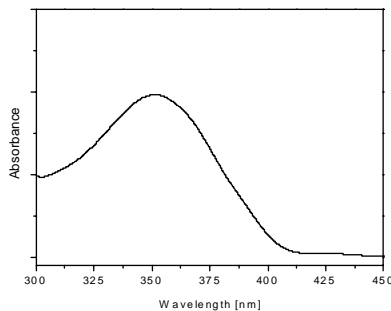
The **ma-N 1400** represents an innovation in negative tone photoresists for flexible use in conventional photolithography (proximity and contact exposure). The resists have a high spectral sensitivity to the i-line (365 nm).

Thickness Range



The **ma-N 1400** is processed by spincoating, spraying or dipping. Film thicknesses from 0.5 to 2.5 µm can be obtained depending on the solid content of the resist solution and the spinning speed.

Spectral Sensitivity



UV-VIS absorbance of **ma-N 1400**

Processing

The **ma-N 1400** series is a photoresist especially designed to generate undercut patterns. The edge profile is easily controlled by variation of the exposure and development parameters. Pattern sidewalls can be produced from nearly vertical to extremely undercut ideally qualifying the resist for metallization processes using lift-off.

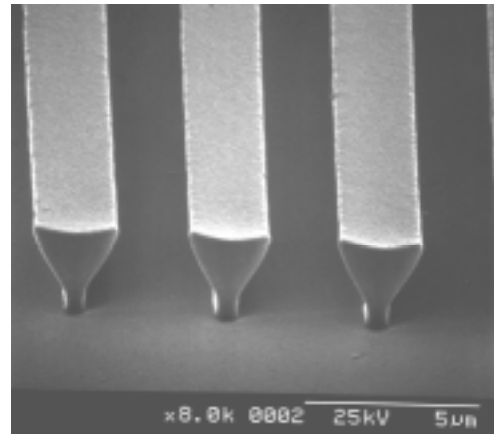
ma-N 1400 can be developed in aqueous-alkaline or aqueous metal-ion-free developers.

Deposition Stability

The **ma-N 1400** resists exhibit a high resistance to acidic and alkaline etching solutions and plating baths (pH 1 to 13) and a good stability in metallization processes.

Stripping

The chemical composition of **ma-N 1400** allows the easy and residue-free resist removal.



2.25 µm lines and spaces in **ma-N 1400**

Pattern Transfer

Depending on the resist thickness a resolution to 0.5 µm is possible using contact exposure. The **ma-N 1400** series shows good adhesion on conventional substrate materials.

Environmental and Health Protection

All harmful organic solvents in resist and developer were substituted and are based on safe solvents.